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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/756,543	01/14/2004	Jae-goo Lee	5649-951DV	3863	
20792	7590 05/11/2004		EXAM	EXAMINER	
MYERS BIGEL SIBLEY & SAJOVEC			NHU, DAVID		
PO BOX 37428 RALEIGH, NC 27627			ART UNIT	PAPER NUMBER	
- ,			2818		
			DATE MAILED: 05/11/2004		

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)					
Office Action Commence	10/756,543	LEE, JAE-GOO					
Office Action Summary	Examin r	Art Unit					
	David Nhu	2818					
The MAILING DATE of this communication app Period for Reply	ars on the cover sheet with the c	orrespondence address					
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) day fill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).					
Status							
1) Responsive to communication(s) filed on 14 Ja	nuary 2004.						
<i>,</i> —	action is non-final.						
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is							
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 45	53 O.G. 213.					
Disposition of Claims							
4) Claim(s) <u>1-14</u> is/are pending in the application.							
4a) Of the above claim(s) is/are withdrawn from consideration.							
· <u> </u>	5) Claim(s) is/are allowed.						
6) Claim(s) <u>1-14</u> is/are rejected.							
7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/o	r election requirement						
	r diedion requirement.						
Application Papers							
9) The specification is objected to by the Examine							
, <u> </u>	epted or b) objected to by the						
Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct							
11) The oath or declaration is objected to by the Ex							
·							
Priority under 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign	priority under 35 U.S.C. § 119(a))-(d) or (f).					
a)⊠ All b)□ Some * c)□ None of:							
1. Certified copies of the priority document		N. 40/400 740					
2. Certified copies of the priority document							
3. Copies of the certified copies of the prior		ed in this National Stage					
application from the International Bureau * See the attached detailed Office action for a list		ed.					
Oce the attached detailed Office detail for a list	or the continue copies have recent	7-1					
	Xu	iRlan					
Attachment(s)							
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)	4)						
 2) Notice of Dransperson's Patent Drawing Review (P10-946) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date <u>01</u>. 		Patent Application (PTO-152)					

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DETAILED ACTIONS

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

2. Claims1-14 are rejected under 35 U.S.C. 102(e) as being anticipated by Nakamura (6,555,481 B2).

Regarding claim 1, Nakamura, figures 1-24, and related text on col. 1-14, (figures 18A-18D, 19A-19D, 20, 22A-22D), disclose an integrated circuit memory device comprising: a semiconductor substrate 1; a plurality of word line (WL) structures 4 on predetermined portions of the semiconductor substrate; WL contact plugs 7, 8, each of which is deposited between adjacent WL structures; storage node contact plugs 11 in electrical contact with predetermined ones of the WL contact plugs; storage node electrodes 16 on the storage node contact plugs; and plate electrode 18 between the storage node electrodes and between the storage node contact plugs.

Regarding to claims 2-5, Nakamura, col. 1-14, also teach wherein the plate electrode extends between lower portions of the storage node contact plugs (see figures 22A-22D); a plate insulating layer 13 between the plate electrode 18 and the storage node contact plug 16 that insulates the plate electrode from the storage node contact plugs; wherein the storage node electrodes are directly on the storage node contact plugs; wherein the WL structures 4, each

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comprises a gate electrode 4b, a gate insulating layer 4a insulating the gate electrode from the semiconductor substrate, and an insulating material covering a top surface and sides of the gate electrode.

Regarding claim 6, Nakamura, figures 1-24, and related text on col. 1-14, (figures 18A-18D, 19A-19D, 20, 22A-22D), disclose an integrated circuit memory device comprising: a semiconductor substrate 1; a pair of spaced apart word line (WL) structures 4 on the substrate; an interlayer insulating layer 5, 9 on the WL structures; a bit line (BL) structure 11 on the interlayer insulating layer 9a, 5 that is transverse to the WL structures; a first capacitor electrode 16 that extends the substrate between adjacent WL structures through the interlayer insulating layer, and beyond the BL structures; a capacitor dielectric 17 on the first capacitor electrode and directly on the BL structures; and a second capacitor electrode 18 on the capacitor dielectric.

Regarding claims 7, Nakamura, also teach wherein the capacitor dielectric is directly on the interlayer insulating layer.

Regarding claim 8, Nakamura, figures 1-24, and related text on col. 1-14, (figures 18A-18D, 19A-19D, 20, 22A-22D), disclose an integrated circuit memory device comprising: a semiconductor substrate 1; a plurality of word line (WL) structures 4 on predetermined portions of the semiconductor substrate; WL contact plugs 7, 8, each of which is deposited between adjacent WL structures; BL structures 11 in electrical contact with a first set of the WL contact plugs; storage node contact plugs on, and electrically connected to, a second set of the WL contact plugs that is different from the first set of the WL contact plugs; storage node electrodes 16 on the storage node contact plugs; a dielectric layer 17 on the storage node

contact plugs and the storage node electrodes; and a plate electrode 18 on the dielectric layer and between the storage node contact plugs and between the storage node electrodes.

Regarding claims 9-14, Nakamura also teach wherein the plate electrode extends between lower portions of the storage node contact plugs (see figures 22A-22D); a plate insulating layer 13 between the plate electrode 18 and the storage node contact plug 16 that insulates the plate electrode from the storage node contact plugs; wherein the storage node electrodes are directly on the storage node contact plugs; wherein the WL structures 4, each comprises a gate electrode 4b, a gate insulating layer 4a insulating the gate electrode from the semiconductor substrate, and an insulating material covering a top surface and sides of the gate electrode.; the b BL structures each comprises a BL and a dielectric layer on a top surface and sides of the BL.

Conclusion

- 3. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure: Kajigaya'365, Aoki'539, Hong'747, Dosaka'628, Ohyu'847, are cited as of interest.
- 4. A shortened statutory period for response to this action is set to expired 3 (three) months and 0 (zero) day from the date of this letter. Failure to respond within the period for response will cause the application to become abandoned(see 710.02 (b)).
- 5. Any inquiry concerning this communication on earlier communications from the examiner should be directed to David Nhu (571)272-1792. The examiner can normally be reached on Monday-Friday from 7:30 AM to 5:00 PM. The examiner's supervisor, David Nelms can be reached on (571)272-1787.

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The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

David Nhu

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May 5, 2004

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